

SOLDER PASTE T3-A-SnPb-35

Low Temperature No-Clean Solder Paste

DESCRIPTION

This solder paste was developed for alloys with the Sn63Pb37 as a standard alloy. It contains a highly active type No-Clean flux with a special formulation for perfect wetting, it fulfils all the requirements for a modern solder paste, which can be used in a high volume electronics manufacturing. As this solder paste leaves only very small amounts of residues after soldering on the PCB, If cleaning has to be done, it can be done easily with most common cleaning processes as the flux formulation contains some rosin.

CHARACTERISTICS

Suitable for fine pitch down to 0,4mm
 Compatible with a wide range of even poor solderable surfaces
 Effective over a wide range of reflow profiles in air or nitrogen
 Produces safe residues - eliminates the need for cleaning
 Temperature range for application 20-35°C

APPLICATION

Solder Paste Printing: Paste was developed for stencil printing with the alloy Sn63Pb37 in combination with solder particle size type 3 (25-45µm) it can be used on every open stencil printing system.

Typical application parameter	0.4-0.65mm Pitch at 150µm stencil thickness
	<0.4mm Pitch at 120µm stencil thickness
Minimum pad width:	180-200µm at 150µm stencil thickness

PHYSICAL PROPERTIES AND DATA

Solder Powder is produced by Atomizing alloys conforming to purity requirements of J-STD-006 careful control of production processes ensures solder powder particle distribution in a spherical shape.

GENERAL PROPERTIES	T3-A-SnPb-35
Alloy	Sn63Pb37
Melting range °C	190
Metal content %	90
Solder powder µm	25-45
Viscosity	190pa.s

STORAGE AND SHELF LIFE

Solder pastes are stored at 2-8°C tightly sealed in the original container, this solder paste has a minimum shelf life of 6 months. Please let the solder paste after storage allow recovering to room temperature before opening the jar for at least 1-2 hours to avoid condensation of humidity on the solder paste surface.